

| L<br>Number | Hits | Search Text                                                                                                                                                                  | DB                                                      | Time stamp          |
|-------------|------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------------------------------------------------------|---------------------|
| 1           | 22   | (thermosetting near resin) and SIMOX                                                                                                                                         | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2004/03/05<br>22:56 |
| 2           | 22   | ((thermosetting near resin) and SIMOX)<br>((thermosetting near resin) with SIMOX)                                                                                            | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2004/03/05<br>22:13 |
| 3           | 19   | ((((thermosetting near resin) and SIMOX)<br>((thermosetting near resin) with SIMOX))<br>and oxidation                                                                        | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2004/03/05<br>22:09 |
| 4           | 16   | (((((thermosetting near resin) and SIMOX)<br>((thermosetting near resin) with SIMOX))<br>and oxidation) and (prevent\$3 with<br>oxidation)                                   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2004/03/05<br>22:09 |
| 5           | 0    | ((thermosetting near resin) and SIMOX)<br>and ((thermosetting near resin) with<br>SIMOX)                                                                                     | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2004/03/05<br>22:13 |
| 6           | 0    | ((thermosetting near resin) and SIMOX)<br>and ((thermosetting near resin) with<br>oxidation)                                                                                 | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2004/03/05<br>22:13 |
| 7           | 0    | (thermosetting near resin) with SIMOX                                                                                                                                        | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2004/03/05<br>22:14 |
| 8           | 5    | SIMOX with (prevent\$5 near4 oxidation)                                                                                                                                      | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2004/03/05<br>22:15 |
| 9           | 293  | ((thermosetting near resin) with<br>oxidation)                                                                                                                               | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2004/03/05<br>22:17 |
| 10          | 52   | ((((thermosetting near resin) with<br>oxidation)) and ((thermosetting near<br>resin) with temperature)                                                                       | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2004/03/05<br>22:19 |
| 11          | 0    | (((((thermosetting near resin) with<br>oxidation)) and ((thermosetting near<br>resin) with temperature)) and Celcius                                                         | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2004/03/05<br>22:19 |
| 12          | 26   | (((((thermosetting near resin) with<br>oxidation)) and ((thermosetting near<br>resin) with temperature)) and (high near<br>temperature)                                      | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2004/03/05<br>22:20 |
| 13          | 17   | (((((thermosetting near resin) with<br>oxidation)) and ((thermosetting near<br>resin) with temperature)) and<br>((thermosetting near resin) with (high<br>near temperature)) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2004/03/05<br>22:30 |
| 14          | 59   | ((thermosetting near resin) with<br>contamination)                                                                                                                           | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2004/03/05<br>22:32 |

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| 15 | 0    | ((thermosetting near resin) with contamination)) and simox                                                                      | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>22:31 |
| 17 | 0    | ((thermosetting near resin) and SIMOX) and (SIMOX near process\$4)                                                              | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>22:33 |
| 16 | 22   | (thermosetting near resin) and SIMOX                                                                                            | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>22:48 |
| 19 | 0    | ((thermosetting near resin) and SIMOX) and ion ) and (ion near beam)                                                            | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>22:33 |
| 18 | 22   | ((thermosetting near resin) and SIMOX) and ion                                                                                  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>22:49 |
| 20 | 22   | ((thermosetting near resin) and SIMOX) and ion ) and temperature                                                                | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>22:50 |
| 21 | 17   | ((thermosetting near resin) and SIMOX) and ion ) and temperature) and (high near temperature)                                   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>22:50 |
| 22 | 17   | ((thermosetting near resin) and SIMOX) and ion ) and temperature) and (high near temperature)) and oxid\$6                      | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>22:41 |
| 23 | 17   | ((thermosetting near resin) and SIMOX) and ion ) and temperature) and (high near temperature)) and oxidation                    | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>22:51 |
| 24 | 15   | ((thermosetting near resin) and SIMOX) and ion ) and temperature) and (high near temperature)) and oxidation) and contaminat\$5 | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>22:51 |
| 25 | 2755 | (thermosetting near resin) and sputtering                                                                                       | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>22:49 |
| 26 | 21   | ((thermosetting near resin) and sputtering) and simox                                                                           | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>22:49 |
| 27 | 21   | ((thermosetting near resin) and sputtering) and simox) and ion                                                                  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>22:49 |
| 28 | 21   | ((thermosetting near resin) and sputtering) and simox) and ion ) and temperature                                                | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>22:50 |

|    |       |                                                                                                                                                                          |                                                         |                     |
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| 29 | 17    | (((((thermosetting near resin) and sputtering) and simox) and ion ) and temperature) and (high near temperature)                                                         | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>22:50 |
| 30 | 17    | (((((thermosetting near resin) and sputtering) and simox) and ion ) and temperature) and (high near temperature)) and oxidation                                          | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>22:51 |
| 31 | 15    | (((((thermosetting near resin) and sputtering) and simox) and ion ) and temperature) and (high near temperature)) and oxidation) and contaminat\$5                       | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>22:54 |
| 32 | 3862  | (250/492.21,440.11,442.11,492.2).CCLS.                                                                                                                                   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>23:09 |
| 33 | 73470 | (thermosetting near resin)                                                                                                                                               | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>23:22 |
| 34 | 3     | ((thermosetting near resin) ) and ((250/492.21,440.11,442.11,492.2).CCLS.)                                                                                               | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>22:56 |
| 35 | 50    | ((thermosetting near resin)near (hold\$3 or pin))                                                                                                                        | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>23:05 |
| 36 | 2     | ((thermosetting near resin)near (hold\$3 or pin)) ) and ion                                                                                                              | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>23:06 |
| 37 | 4367  | (250/492.21,440.11,442.11,492.2,398).CCLS.                                                                                                                               | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>23:09 |
| 38 | 0     | ((thermosetting near resin) with oxidation) and ((250/492.21,440.11,442.11,492.2,398).CCLS.                                                                              | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>23:23 |
| 39 | 3     | Simox and (thermosetting near resin) and (holder or pin)                                                                                                                 | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>23:55 |
| 40 | 23    | Simox and ((thermosetting near resin)or ((epoxy or acrylic or silicone or urethane or polyimide or silicon) near resin)) and (holder or pin)                             | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>23:58 |
| 41 | 23    | (Simox and ((thermosetting near resin)or ((epoxy or acrylic or silicone or urethane or polyimide or silicon) near resin)) and (holder or pin)) and ion                   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>23:58 |
| 42 | 23    | ((Simox and ((thermosetting near resin)or ((epoxy or acrylic or silicone or urethane or polyimide or silicon) near resin)) and (holder or pin)) and ion) and temperature | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/05<br>23:58 |

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| 43 | 6 | ((Simox and ((thermosetting near resin)or ((epoxy or acrylic or silicone or urethane or polyimide or silicon) near resin)) and (holder or pin)) and ion) and temperature) and oxidation                                       | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/06<br>00:00 |
| 45 | 2 | (((((Simox and ((thermosetting near resin)or ((epoxy or acrylic or silicone or urethane or polyimide or silicon) near resin)) and (holder or pin)) and ion) and temperature) and oxidation) and contaminat\$5) and sputter\$4 | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/06<br>00:01 |
| 44 | 4 | (((((Simox and ((thermosetting near resin)or ((epoxy or acrylic or silicone or urethane or polyimide or silicon) near resin)) and (holder or pin)) and ion) and temperature) and oxidation) and contaminat\$5                 | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/06<br>00:09 |

| L Number | Hits | Search Text                                                                                                                                                                                                                                         | DB                                                      | Time stamp          |
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| 1        | 0    | 2003/0052282                                                                                                                                                                                                                                        | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/06<br>00:50 |
| 2        | 38   | "0052282"                                                                                                                                                                                                                                           | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/06<br>00:51 |
| 3        | 1    | 10/157941                                                                                                                                                                                                                                           | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/06<br>01:06 |
| 4        | 828  | (250/492.21,440.11).CCLS.                                                                                                                                                                                                                           | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/06<br>01:06 |
| 5        | 0    | resin and Simox and<br>((250/492.21,440.11).CCLS.)                                                                                                                                                                                                  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/06<br>01:07 |
| 6        | 27   | resin and ((250/492.21,440.11).CCLS.)                                                                                                                                                                                                               | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/06<br>01:07 |
| 7        | 2    | (resin and ((250/492.21,440.11).CCLS.))<br>and thermosetting                                                                                                                                                                                        | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/06<br>01:10 |
| 8        | 6    | (resin and ((250/492.21,440.11).CCLS.))<br>and ((thermosetting or epoxy or acrylic<br>or silicon or silicone or urethane or<br>polyimide) near resin)                                                                                               | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/06<br>01:17 |
| 9        | 62   | simox and ((thermosetting or epoxy or<br>acrylic or silicon or silicone or<br>urethane or polyimide) near resin) and<br>oxidation                                                                                                                   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/06<br>01:34 |
| 10       | 46   | (simox and ((thermosetting or epoxy or<br>acrylic or silicon or silicone or<br>urethane or polyimide) near resin) and<br>oxidation) and (ion near (beam or<br>implant\$7))                                                                          | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/06<br>01:33 |
| 11       | 29   | ((simox and ((thermosetting or epoxy or<br>acrylic or silicon or silicone or<br>urethane or polyimide) near resin) and<br>oxidation) and (ion near (beam or<br>implant\$7))) and (prevent\$7 with<br>(contamination or oxidation))                  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/06<br>01:19 |
| 12       | 29   | ((simox and ((thermosetting or epoxy or<br>acrylic or silicon or silicone or<br>urethane or polyimide) near resin) and<br>oxidation) and (ion near (beam or<br>implant\$7))) and (prevent\$7 with<br>(contamination or oxidation or<br>sputtering)) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/06<br>01:27 |
| 13       | 14   | ((simox and ((thermosetting or epoxy or<br>acrylic or silicon or silicone or<br>urethane or polyimide) near resin) and<br>oxidation) and (ion near (beam or<br>implant\$7))) and (prevent\$7 with<br>(contamination or sputtering))                 | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/06<br>01:20 |

|    |      |                                                                                                                                                                                                                                    |                                                         |                     |
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| 14 | 29   | ((simox and ((thermosetting or epoxy or acrylic or silicon or silicone or urethane or polyimide) near resin) and oxidation) and (ion near (beam or implant\$7))) and (prevent\$7 near4 (contamination or oxidation or sputtering)) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/06<br>01:25 |
| 15 | 29   | ((simox and ((thermosetting or epoxy or acrylic or silicon or silicone or urethane or polyimide) near resin) and oxidation) and (ion near (beam or implant\$7))) and (prevent\$7 near5 (contamination or oxidation or sputtering)) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/06<br>01:33 |
| 16 | 3138 | ((thermosetting or epoxy or acrylic or silicon or silicone or urethane or polyimide) near resin) and (ion near (beam or implant\$7))                                                                                               | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/06<br>01:35 |
| 17 | 2    | ((((thermosetting or epoxy or acrylic or silicon or silicone or urethane or polyimide) near resin) with (prevent\$7 near4 (contamination or oxidation or sputtering))) and (ion near (beam or implant\$7)))                        | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/06<br>01:58 |
| 18 | 13   | ((((thermosetting or epoxy or acrylic or silicon or silicone or urethane or polyimide) near resin) with (prevent\$7 near4 (contamination or oxidation or sputtering))) and ((ion or electron)near (beam or implant\$7)))           | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/06<br>01:59 |